2SK3628

Silicon N-channel power MOSFET

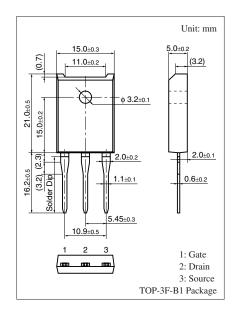
For hihg-speed switching

Features

- Avalanche energy capability guaranteed
- High-speed switching
- Low ON resistance Ron
- No secondary breakdown

Absolute Maximum Ratings $T_C = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Drain-source surrender voltage	V _{DSS}	230	V	
Gate-source surrender voltage	V _{GSS}	±30	V	
Drain current	ID	20	А	
Peak drain current	I _{DP}	80	А	
Avalanche energy capability *	EAS	570	mJ	
Power	P _D	100	W	
dissipation $T_a = 25^{\circ}C$		3		
Channel temperature	T_{ch}	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	

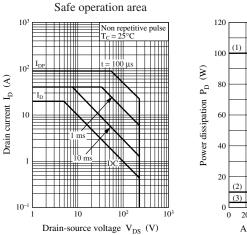


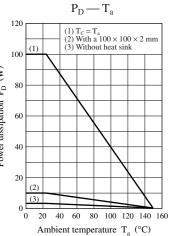
Note) *: L = 2.23 mH, $I_L = 20 \text{ A}$, $V_{DD} = 50 \text{ V}$, 1 pulse, $T_a = 25^{\circ}\text{C}$

Electrical Characteristics $T_C = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Gate-drain surrender voltage	V _{DSS}	$I_D = 1 \text{ mA}, V_{GS} = 0$	230			V
Diode forward voltage	V _{DSF}	$I_{DR} = 20 \text{ A}, V_{GS} = 0$			-1.5	V
Gate threshold voltage	V _{th}	$V_{DS} = 25 \text{ V}, I_D = 1 \text{ mA}$	1.7		3.7	V
Drain-source cutoff current	I _{DSS}	$V_{DS} = 184 \text{ V}, V_{GS} = 0$			100	μΑ
Gate-source cutoff currentt	I _{GSS}	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0$			±1	μΑ
Drain-source on resistance	R _{DS(on)}	$V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$		65	85	mΩ
Forward transfer admittance	Y _{fs}	$V_{DS} = 25 \text{ V}, I_D = 10 \text{ A}$	7	14		S
Short-circuit forward transfer capacitance (Common-source)	C _{iss}	$V_{DS} = 25 V, V_{GS} = 0, f = 1 MHz$		2300		pF
Short-circuit output capacitance (Common-source)	C _{oss}			330		pF
Reverse transfer capacitance (Common-source)	C _{rss}			30		pF
Turn-on delay time	t _{d(on)}	$V_{DD} \approx 100 \text{ V}, \text{ I}_{D} = 15 \text{ A}$		35		ns
Rise time	t _r	$R_{L} = 6.7 \ \Omega, \ V_{GS} = 10 \ V$		26		ns
Turn-off delay time	t _{d(off)}			220		ns
Fall time	t _f			36		ns

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.





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